

## Keynote Speakers



**Mr Siau Guan Wah**  
Tekmark Group

**Mr Siau Guan Wah** is the Vice President of Sales for Tekmark Group.

As the leader of the company's regional sales function across ASEAN, Siau is responsible for the business performance for the company.

Siau has 20 years of deep industrial and global experience in electronic test & measurement, as well as network telecommunication industry, working in MNCs from America and Europe.

Siau graduated from Nanyang Technology University with a bachelor's degree in Electronic Engineering in 1999, and holds a Master of Business Administration degree from Murdoch University. He is also currently pursuing his Doctor of Business Administration (DBA) from IPE Management School Paris.



**Professor Dr Pierre Brunswick**  
Neuromem Technologies PTE LTD

**Professor Dr Pierre** brings over 40 years of international experience in business development, sales, marketing, engineering, finance, and incubators to his role of CEO at Neuromem. Throughout his career, he has managed a region covering 94 countries and 9 local offices. He has helped customers complete large projects and implement the right strategy to grow, merge, acquire new businesses, go public, hire the necessary talent and establish local offices as well as form joint ventures.

Pierre has developed significant local government relationships (including technology transfers, big infrastructure projects, and top technology specific programs), working with financial institutions and elaborated many educational programs, including incubators for start-ups.

Before becoming CEO and cofounder of NeuroMem Technologies in March 2017, Pierre (Elected Knight from the Russian Academy of Sciences in 2005) was the chair of the board of directors of EloCath (the holding company of UNANALAC in UAE and PBRC in Geneva) based in Singapore where the group was focusing on incubators and promoting new technologies and talents. ELOCATH has partnered with some of the best engineering companies around the world, promoting leading disruptive technologies in key sectors.

## Special Session



**Mr Kalai Selvan Subramaniam**  
Infinecs Systems Sdn Bhd

**Kalai Selvan Subramaniam** has more than 28 years of experience in the electronics/semiconductor industry with leadership positions in Technology Start-Ups to Tier-1 Semiconductor MNCs. He is passionate in setting up teams from ground up and building efficient functional engineering and technical organizations/start-ups. He holds BEE (Hons) and MEng from UTM. He is the Co-Founder CEO of Infinecs Systems Sdn Bhd. Prior to that, he was the General Manager of USains Infotech Sdn Bhd. He started his career in Motorola Semiconductors and spent a total of 12 years there with 3 years in Austin, Texas, and 5 years in Singapore. Kalai joined My-MS, a start-up company in Malaysia, as a pioneer team member. He led and set-up the IC Design capability from the ground up to develop Embedded & Security Memory SOCs. Kalai also worked at Intel Corporation for over 10 years in a managerial and leadership role in Oregon, USA, and Penang, Malaysia. Kalai is a senior member of IEEE and active contributor to IEEE Malaysia section and chapters. He has held a number of executive portfolios in local IEEE section and chapters. He was the Chair of the Malaysia IC Design Association (MICDA) and actively participates in the National Electronics industry development forums/committees especially with regards to uplifting the Semiconductors and Electronics Design areas.



## Plenary Speakers



**Dr Charles F Campbell**

Qorvo, USA

**Dr Charles F Campbell** received his BSEE, MSEE, and PhD degrees from Iowa State University in 1988, 1991, and 1993 respectively. From 1993 to 1998, he was with Texas Instruments, involved with microwave module design and MMIC development. Since 1998, he has been with various divisions of TriQuint Semiconductor where he has held positions of Design Team Leader, Design Engineering Director, and Design Engineering Fellow. He is currently an Engineering Senior Fellow with the Infrastructure and Defense Products Division of Qorvo. A Fellow of the IEEE, he has served on the Editorial Board for IEEE Transactions on Microwave Theory and Techniques, general chair for the 2015 Compound Semiconductor Integrated Circuits Symposium, and the IEEE Microwave Prize selection committee. He has authored or co-authored over 50 journal and conference papers, and authored an online book chapter on MMIC power amplifier design.



**Dr Markus Gardill**

InnoSenT GmbH, Germany

**Dr Markus Gardill** (S'11 – M'15) was born in Bamberg, Germany in 1985. He received the Dipl-Ing and Dr-Ing degree in Information Systems and Multimedia Technology/Electrical Engineering from the Friedrich-Alexander-University Erlangen-Nürnberg, Germany, in 2010 and 2015 respectively. In 2010, he joined the Institute for Electronics Engineering at the Friedrich-Alexander-University Erlangen-Nürnberg as a Research Assistant and Teaching Fellow. From 2014 to 2015, he was the Head of the Radio Communication Technology Team. In late 2015, he joined Robert Bosch GmbH as an R&D Engineer for optical and imaging metrology systems, leading the cluster of non-destructive testing for the international production network. In 2016, he joined InnoSenT GmbH as Senior Software Developer for automotive radar signal processing algorithms.

During his affiliation with the Institute for Electronics Engineering, he taught Circuits & Systems for Communication, Digital Electronic Systems, Programmable Electronic Systems, and Wireless Automotive Electronics. He is currently a Lecturer for Wireless Automotive Electronics at the Friedrich-Alexander University Erlangen-Nürnberg. His main research interests include radar and communication systems, antenna (array) design, and signal processing algorithms. His specific interest is in spatio-temporal processing such as beamforming and direction-of-arrival estimation with a focus on combining the worlds of signal processing and microwave/electromagnetics. Dr Gardill is a member of the IEEE Microwave Theory and Techniques Society (IEEE MTT-S) and MTT-S Technical Coordinating Committee Digital Signal Processing (MTT-9). He regularly acts as reviewer and TPRC member for several journals and conferences. He is selected as a Distinguished Microwave Lecturer (DML) for the DML term 2018 – 2020 with a presentation focusing automotive radar systems.



**Mr Francis Leong**

Optenni, Singapore

**Francis Leong** started his career in 1992 as a Microwave Circuit Design Engineer, developing low-noise amplifiers, filters, and waveguides. He then pursued his career in the Test & Measurement group in Hewlett-Packard (which subsequently was spun off as Agilent Technologies), taking on roles in application consulting and managing a device characterization laboratory. Francis left Agilent in 2005 and continued in the RF/microwave design sector focusing in the Asia Pacific region. He is currently a consultant for Optenni, which specializes in antenna matching and RF front end integration..



**Mr Lee Ken Yong**

Keysight Technologies, Malaysia

**Mr Lee Ken Yong** is a Wireless Application Consultant with Keysight Technologies' SAP field division. He graduated with a Bachelor's Degree in Physics from University Malaya, Malaysia. He has 10 years of experience in the wireless test and measurement industry. In his current role, he is responsible in providing technical expertise on Keysight's wireless product in the area of SAP. Society (IEEE MTT-S) and MTT-S Technical Coordinating Committee Digital Signal Processing (MTT-9). He regularly acts as reviewer and TPRC member for several journals and conferences. He is selected as a Distinguished Microwave Lecturer (DML) for the DML term 2018 – 2020 with a presentation focusing automotive radar systems.



**Mr Bob Ng**

Rohde & Schwarz, Malaysia

**Bob Ng** received his Bachelor's Degree in Electronics Engineering from Multimedia University in 2004. He started his career as an RF Product Engineer at Agilent Technologies, where he was involved in manufacturing and quality of high performance spectrum analyzers up to millimeter wave. He further expanded his breadth in test and measurement (from RF to digital to LF) in 2008 as a pioneer Application Engineer and then Solutions Consultant Manager for a local start-up company representing Agilent Technologies. He has been with Rohde & Schwarz since 2012 as their Systems and Application Engineering Manager. He has special interest in multi-disciplinary applications, whereby traditional test and measurement concepts are applied in other disciplines such as chemical, biology, etc. He is also passionate about innovation culture and how technology can make a positive impact in society.



**Mr John Tay**

MCMC, Malaysia

**Mr John Tay** is the Director of the Digital Lifestyle & Society department at the Malaysian Communications and Multimedia Commission (MCMC). He has been with the Commission for the past 15 years. John has more than 30 years of experience in the ICT industry and holds a BSc in Computer Science from Oklahoma State University, USA and an MBA from Federation University, Australia. John has many years of work experience in the Banking, Aerospace, Oil and Gas, IT Services and Telecommunications industries. He has also worked overseas for numerous years in the healthcare, pharmaceutical and aerospace industries.

In MCMC, John is responsible for promoting and facilitating Digital Lifestyle Malaysia (DLM) and myMaker Initiative on Connected Lifestyles and Internet of Things. Digital Lifestyle Initiative is a platform to promote Industry 4.0 and Internet of Things services and applications and to encourage the development of contents as a driver towards a smart digital nation, while the myMaker initiative is to promote creative and innovative maker platform among maker communities as the grass root of Internet of Things and Industry 4.0.



**Dr Usman Sarwar**

Intel Malaysia, Malaysia

**Dr Usman Sarwar** is a Technologist and Validation Architect working on IoT connectivity technologies in Intel's IoT group, with 15 years of R&D and software development experience. He has diverse technical background by working on areas related to IoT connectivity technologies and protocols, middleware protocol systems, as well as applications. He has worked on Intel IoT gateway technologies for different use-cases. Currently, he is working on the time-sensitive networking for industrial and automotive technologies. He is also working with different industrial partners to define the next generation Industrial systems communication certification within Avnu Alliance. Dr Usman is the Intel liaison for Intel with ZigBee Alliance where Intel has presence of edge gateways. He holds more than 23 patents, published 23 international papers, and contributed to ITU-T resolutions.



**Mr Alan Gooi**

FILPAL (S) Pte Ltd, Singapore

**Alan Gooi** had been a test & measurement hardware guy for the past 15 years. Graduated in Microelectronics, and join Intel as a Failure Analysis engineer, followed by a move on the test & measurement equipment maker Tektronix & Keithley. Then he started his own company distributing Rohde & Schwarz equipment. He joined FILPAL and become director of distribution after the recent merger and acquisition activities. FILPAL owns software design tools and affordable engineering software in the market either for teaching or research. So this results in a synergy providing an end-to-end solution, where you can do design, synthesis, simulation, prototyping and characterization of microwave and mmwave devices from scratch, and correlate your fabricated design in the real world versus the design in the ideal world.



## Plenary Speakers



**Prof Sorin Cristoloveanu**  
Grenoble Polytechnic Institute, France

**Professor Dr Sorin Cristoloveanu** received his PhD (1976) in Electronics and the French Doctorat ès-Sciences in Physics (1981) from Grenoble Polytechnic Institute, France. He is currently the Director of Research at the French National Center for Scientific Research (CNRS). He previously worked at JPL (Pasadena), Motorola (Phoenix), and the Universities of Maryland, Florida, Vanderbilt, Western Australia, and Kyungpook (World Class University project). He also served as the Director of the LPCS Laboratory and the Center for Advanced Projects in Microelectronics, the initial seed of Minatec center.

Dr Sorin authored more than 1,100 technical journal papers and communications for international conferences (including 160 invited contributions). He is the author/editor of 28 books and he has organized 25 international conferences. His expertise is in the area of electrical characterization and modeling of semiconductor materials and devices, with special interest in silicon-on-insulator structures. He has supervised more than 90 PhD completions. With his students, he has received 13 Best Paper Awards, an Academy of Science Award (1995), and the Electronics Division Award of the Electrochemical Society (2002). He is a Fellow of IEEE, a Fellow of the Electrochemical Society, and Editor of Solid-State Electronics. He is the recipient of the IEEE Andy Grove Award in 2017.



**Prof Dr Samir Iqbal**  
University of Texas At Arlington, USA

**Professor Dr Samir Iqbal** earned his PhD from Purdue University, USA, in 2007. His research is focused on enhancing sensitivity and selectivity of solid-state sensors and understanding the physics of nano-bio interfaces and molecular interactions. He is a senior member of IEEE and a member of the Biomedical Engineering Society, American Physical Society, Biophysical Society, and National Academy of Innovators. He has published about 60 journal articles and presented at more than 100 conferences. He is a Distinguished Lecturer for two IEEE Societies (IEEE Nanotechnology Council and IEEE EMBS). He has received many research, teaching, mentoring, and service awards.



**Prof Kuei-Shu Chang-Liao**  
National Tsing-Hua University, Taiwan

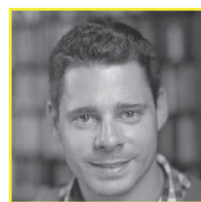
**Professor Dr Kuei-Shu Chang-Liao** received his Bachelor of Science and Master of Science degrees in Telecommunication and Electronics from National Chiao Tung University in 1984 and 1989 respectively and his PhD in Electrical Engineering from National Taiwan University in 1992. In 1992, Dr Chang-Liao joined the National Tsing Hua University where he has been a Professor of the Department of Engineering and System Science since 1999. In 2000, he was a visiting Research Fellow at the Department of Electrical Engineering of Yale University, where he was involved in Flash memory and charge pumping measurement. From 2007 to 2010, he served as the Associate Chairman of the Department of Engineering and System Science. His current research interests include high-k/metal gate stack processes in FinFET, Ge or SiGe MOS devices, charge-trapping flash memory devices, and trap analysis in MOS device by charge pumping measurement. Dr Chang-Liao is a Distinguished Lecture of IEEE EDS, senior member of IEEE, and member of the Electrochemical Society. He served as the Editor of IEEE Electron Device Letters from 2012 to 2015. He received the excellent Industry-Academic Research Award from the Ministry of Education in 2003. He has published over 300 papers in prestigious journals and conferences. He has also chaired and served as committee members in several international conferences.



**Prof Taiichi Otsuji**  
Tohoku University, Japan

**Prof Dr Taiichi Otsuji** is a Professor at the Research Institute of Electrical Communication (RIEC), Tohoku University, Japan. He received his Bachelor of Science and Master of Science degrees in Electronic Engineering from Kyushu Institute of Technology, Japan, in 1982 and 1984 respectively, and his Doctorate in Electronic Engineering from Tokyo Institute of Technology, Japan in 1994. From 1984 to 1999, he worked for NTT Laboratories in Kanagawa, Japan. In 1999, he joined Kyushu Institute of Technology as an Associate Professor and subsequently became a professor in 2002 before joining RIEC in 2005.

His current research interests include terahertz electronic, photonic and plasmonic materials/devices and their applications. He has authored and co-authored 250 peer-reviewed journal papers and more than 490 conference proceedings, including 150 invited presentations, and holds 11 Japanese and 7 US patents. He was awarded the Outstanding Paper Award of the 1997 IEEE GaAs IC Symposium and has been an IEEE Electron Device Society Distinguished Lecturer since 2013. He is a Fellow of the IEEE (MTT-S, ED-S, Photonics-S, and Sensors Council) and JSAP (Japan Society of Applied Physics), a senior member of the OSA, and a member of the MRS, SPIE, and IEICE.



**Dr Matthew Cole**  
Bath University, UK

**Dr Matthew Cole** is an Associate Professor in the Department of Electronic and Electrical Engineering at the University of Bath, UK, where he leads a research team investigating the heterogeneous integration of chemical vapour deposited aligned 1D and 2D nanomaterials in nanoscale electronics devices. Dr Cole is a Fellow of the Institute of Materials, Minerals and Mining (FIMMM) and the Institute of Engineering and Technology (FIET), a Chartered Engineer (CEng), a Chartered Scientist (CSci), and a Chartered Physicist (CPhys). Dr Cole's research airs on the side of pragmatism; he is a named Forbes 30 under 30 (2016) and is one of the MIT Technology Reviews top 35 emerging Innovators in Europe (2017). His awards include the Sir MacFarlane Medal from the Royal Academy of Engineering, the Sir Kroto Medal from the NanoSmat Society, the Silver Medal from the Institute of Materials, Minerals, & Mining, and the Sir Royce Medal from the Institute of Engineering & Technology. Dr Cole has spent time as a Visiting Scholar at Harvard University and as a Research Associate at Sharp Laboratories of Europe. He has held the Isaac Newton Trust Fellowship (2012), a Winston Churchill Trust Fellowship (2012 – 2013), an International Young Scientist Research Fellowship (2013 – 2014), the CAS President's International Fellowship (2015-2017), and Cambridge University's Oppenheimer Research Fellowship (2014 – 2017).



**Ir Dr Lee Meng Chuan**  
Intel Malaysia, Malaysia

**Ir Dr Lee Meng Chuan** received his B Eng (Hons) in Electronics, M Eng in Microelectronics, and PhD in Engineering from Multimedia University, Cyberjaya Campus, Malaysia. He obtained ASQ Certified Six Sigma Black Belt since 2011. He is a Professional Engineer registered with the Board of Engineers, Malaysia, a Corporate Member of IEM, and a member of the IEM Electronics Engineering Technical Division since 2017. Currently, he works for Intel Malaysia as Product Stress Development Quality and Reliability Manager who owns the charter to devise and enable reliability stress capability for Intel products. His research interest includes reliability characterization and study on NVM and semiconductor logic devices.



**Dr Mohd Khairuddin Md Arshad**  
Universiti Malaysia Perlis, Malaysia

**Dr Mohd Khairuddin Md Arshad** is an Associate Professor at the School of Microelectronic Engineering, Universiti Malaysia Perlis. He received his Doctorate in Engineering Science from the Université Catholique de Louvain (UCL), Louvain-la-Neuve, Belgium, in 2013. Prior to joining UniMAP in 2005, he had worked at Agilent Technologies (M) Sdn Bhd in Penang, where he was a Product Engineer for the Motion Control Department, manufacturing various printer sensors. He later joined ON Semiconductor (M) Sdn Bhd in Senawang, Malaysia, as a Postgraduate Researcher involved in development of Under-Bump-Metallurgy (UBM) for Flip-Chip Packaging, Subsequently, for his doctorate studies, he was involved in developing ultra-thin body and thin buried oxide (UTBB) for advanced low power mobile transistor application. His current research is related to Field-Effect device technology and biosensors.

With the experience gained in the industry and academia on semiconductor packaging, fabrication process, and device technology, he received various national and two Royal Society-Newton Ungku Omar mobility grants. He is one of the founding members and current Chair of IEEE Malaysia Section Sensors & Nanotechnology Joint Councils Chapter (CH10820). He is also a Professional Engineer and serves as a member of the Engineering Accreditation panel of the Board of Engineers Malaysia (BEM) and the Malaysian Qualifications Agency (MQA).



**Mr Tan Chan Lik**  
Infineon, Malaysia

**Tan Chan Lik** received his MSc in Electrical Engineering, majoring in Solid State Physics, from the National Taiwan University in 1995. He joined Infineon Technologies, Kulim, in 2005 as one of the members of the start-up team that focused on process integration and technology transfer and was a Technical Lead in the transfer of several Smart Power Technologies in Infineon Kulim, Malaysia. He has more than 20 years of experience in process integration and process development of CMOS Logic/SRAM/Flash and Power Technologies. Currently, he is Principal Engineer for Smart Power Technologies Process Integration and Technology Development for Power SOI in Infineon Kulim. He has published more than 10 technical international publications and is also a senior member of IEEE, Electron Device Society. He is an appointed member of the IAP (Industrial Advisory Panel) for UTHM (University Tun Hussein Onn Malaysia) in Faculty of Electrical & Electronics Engineering. He is also a co-supervisor of industrial post-graduate programs for the Faculty of Microelectronics in UniMAP (University Malaysia Perlis).



## Plenary Speakers



**Prof Dr Zhihua Wang**  
Tsinghua University, China

**Professor Dr Zhihua Wang** (M'99-SM'04-F'17) received his Bachelor of Science, Master of Science, and PhD degrees in Electronic Engineering in 1983, 1985, and 1990 respectively from Tsinghua University, China, where he has served as Full Professor and Deputy Director of the Institute of Microelectronics since 1997 and 2000. He was a Visiting Scholar at CMU (1992 – 1993) and KU Leuven (1993 – 1994) and was a Visiting Professor at HKUST (September 2014 – March 2015). His current research mainly focuses on CMOS RFIC and biomedical applications, involving RFID, PLL, low-power wireless transceivers, and smart clinic equipment combined with leading edge RFIC and digital image processing techniques. He has co-authored 12 books/chapters, over 183 (480) papers in international journals (conferences), over 244 (29) papers in Chinese journals (conferences) and holds 123 Chinese and 8 US patents. Prof Wang has served as the chairman of IEEE SSCS Beijing Chapter (1999 – 2009), an AdCom Member of the IEEE SSCS (2016 – 2019), a technology program committee member of the IEEE ISSCC (2005 – 2011), a steering committee member of the IEEE A-SSCC (since 2005), the technical program chair for A-SSCC 2013, a guest editor for IEEE JSSC Special Issues (December 2006, December 2009, and November 2014), an associate editor of IEEE Trans on CAS-I, CAS-II and IEEE Trans on BioCAS, and other administrative/expert committee positions in China's national science and technology projects.



**Dr Hyeon-Min Bae**  
KAIST, South Korea

**Professor Dr Hyeon-Min Bae** received his Bachelor of Science in Electrical Engineering from Seoul National University, South Korea, in 1998 and his Master of Science and PhD degrees in Electrical and Computer Engineering from the University of Illinois at Urbana-Champaign, Illinois, USA, in 2001 and 2004 respectively. From 1995 to 1996, he served his military duty in Dokdo in the East Sea. From 2001 to 2007, he led the analog and mixed-signal design aspects of OC-192 MLSE based EDC ICs at Intersymbol Communications, Inc in Champaign, Illinois, USA. From 2007 to 2009, he was with Finisar Corporation in Sunnyvale, California, USA, after its acquisition of Intersymbol Communications Inc. Since 2009, he has been on the faculty of Electrical Engineering at Korea Advanced Institute of Science and Technology (KAIST) in Daejeon, South Korea, where he is currently an Associate Professor.

In 2010, he founded Terasquare, Inc in Seoul, a venture-funded fabless semiconductor start-up, which provided low power all digital 100 Gb/s IC solutions. Teresquare, Inc was acquired by Gigpeak in 2015. In 2013, He also founded OBELab, Inc in Seoul, a bio startup that manufactures portable functional brain imaging systems. His research interest spans across a wide range of topics especially in wireline communication and medical imaging systems. Prof Bae received the Excellence Award from the National Academy of Engineering of Korea in 2013 and the 2006 IEEE Journal of Solid-State Circuits Best Paper Award.



**Ir Dr Harikrishnan Ramiah**  
University of Malaya, Malaysia

**Ir Dr Harikrishnan Ramiah** is currently an Associate Professor at Department of Electrical Engineering of the University of Malaya, Malaysia, working in the area of RFIC and RF Energy Harvesting System design. He received his Bachelor of Engineering (Hons), Master of Science, and PhD degrees in Electrical and Electronic Engineering, in the field of Analog and Digital IC design from Universiti Sains Malaysia in 2000, 2003, and 2008 respectively. In the year 2003, he was with SiresLabs Sdn Bhd, Malaysia, working on 10Gbps SONET/SDH Transceiver solution. In 2002, he was attached to Intel Technology Sdn Bhd, performing high frequency signal integrity analysis for high speed digital data transmission and developing Matlab spread sheet for Eye diagram generation to evaluate signal response for FCBGA and FCMMAP packages. He currently leads the Analog, Digital and RF Research Group at the University of Malaya.

Harikrishnan was a recipient of Intel Fellowship Grant Award from 2000 till 2008. He is a Chartered Engineer of Institute of Electrical Technology (IET), Fellow of IET, Senior Member of IEEE, and also a Professional Engineer registered under the Board of Engineers, Malaysia. He is a member of The Institute of Electronics, Information, and Communication Engineers (IEICE). His research work has resulted in several IEEE transaction publications. His main research interest includes Analog Integrated Circuit Design, RFIC Design, VLSI system design, and RF Energy Harvesting Power Management Module Design.



**Dr Vivek De**  
Intel Corporation, USA

**Dr Vivek De** is an Intel Fellow and Director of Circuit Technology Research in Intel Labs. He is responsible for providing strategic technical directions for long-term research in future circuit technologies and leading energy efficiency research across the hardware stack. He has 249 publications in refereed international conferences and journals and 209 patents issued, with 26 more patents filed (pending). He received an Intel Achievement Award for his contributions to integrated voltage regulator technology. He received a Best Paper Award at the 1996 IEEE International ASIC Conference and nominations for Best Paper Awards at the 2007 IEEE/ACM Design Automation Conference (DAC) and 2008 IEEE/ACM International Conference on Computer-Aided Design (ICCAD). One of his publications was recognized in the 2013 IEEE/ACM Design Automation Conference (DAC) as one of the Top 10 Cited Papers in 50 Years of DAC. He received a PhD in Electrical Engineering from Rensselaer Polytechnic Institute in Troy, New York. He is a Fellow of the IEEE.



**Mr Mohd Parid Sulaiman**  
Intel Malaysia, Malaysia

**Mr Mohd Parid Sulaiman** is the Engineering Director for Strategic Program at Intel Malaysia's. He received his Bachelor of Engineering (Hons) from Monash University, Australia, Master of Engineering (Honorary) from University Malaysia Perlis (UniMAP), and Master of Business Administration (MBA) from Open University Malaysia.

He started his career at Intel as a Product Engineer and throughout the years, he has held numerous positions in product engineering, assembly & test operation, quality & reliability, new product development, and transfer of technology and key programs in Intel's factory organizations and various business units. He then moved to board business and took on an engineering and program management role as the Worldwide Product Engineering Director for the Intel Client Board Division, covering headcount in US, China, Malaysia, and Taiwan. He was involved in the new Intel motherboards product design development, outsourcing, and managing issues at ODMs factory and customers sites.

After his board business stint, he worked as Module/Engineering/Business Development Director for Malaysia Design Center - Site Strategic Initiatives in building local ecosystem. He had been invited to various conferences and seminars, which include MCMC, TVET, Industrial, IEEE flagship conferences and many others.



**Mr Lee Chang Fatt**  
Genetron, Malaysia

**Lee Chang Fatt** is a Senior Field Marketing Engineer at Anritsu, dedicated to the test solution for the latest mobile and wireless technology development. The scopes of support range from leading R&D and design verification to conformance testing and mass production in the Asean Region. Before joining Anritsu, he worked under A\*STAR's Institute for Infocomm Research (I2R) for wireless communication planning in national smart sensor deployment and electrical vehicle (EV) development project. In his early career, he used to design cellular products from concept until product realization. This formed a solid foundation for his current role in Anritsu in providing technical consultancy. He has a Bachelor's Degree in Telecommunication Engineering from Universiti Teknologi Malaysia.



**Mr Daniel Kho**  
SynVue, Malaysia

**Daniel Koh** has spent more than 16 years working on digital IP design and test. He has real experience in design and verification of safety and mission critical DSP and RISC processor subsystems for Altera, Motorola, and ASML BV. He has extensive experience in designing complex SoC subsystems and bus interfaces, and pioneered hardware-based transaction-level modelling. Daniel is a registered Certified Professional Trainer and a Certified International Professional Manager of the IPMA, United Kingdom. Daniel is also a Senior Member of the IEEE. He contributed to the IEEE P1076-2008 VHDL standard and continues advancing microelectronics industry through IEEE. He has served as a reviewer for several international journals and conferences. He had worked in Altera, Motorola, and Benchmark before establishing his own company, SynVue Sdn Bhd, which focuses on IC Design services and training. He works on expert design and verification consulting services, using leading-edge design and verification languages, tools, and techniques. He also does architecture definition and review, methodology definition and review, code design review, as well as custom design and verification. His passions include mentoring and training on FPGA / ASIC digital design and simulations, SoC bus architecture design, and DSP.



**Dr Eloi Marigó Ferrer**  
SilTerra, Malaysia

**Dr Eloi Marigó** was born in Barcelona, Spain, in 1985. He received his Bachelor's Degree in Engineer Telecommunications, Master's Degree in Micro and Nanoelectronics, and PhD in Electrical Engineering from Universitat Autònoma de Barcelona, Bellaterra, Spain, in 2008, 2009, and 2012 respectively.

In 2013, he joined the Department of Technology Development of SilTerra Malaysia Sdn Bhd as a Senior Engineer, and in 2018, he became a Principal Engineer. His current research interests include the design, simulation, fabrication, and characterization of radiofrequency CMOS micro/nano electromechanical (MEMS/NEMS) systems and their packaging. He has broad experience in different type of MEMS ranging electrostatic NEMS, surface, and bulk acoustic wave devices, ultrasonic transducers, optical micromirrors, accelerometers, and more recently, ultrasonic transducers.